Abstract

A heater chip for thermocompression bonding, where the degree of heating at the thermocompression bonding part does not vary among individual heater chips and durability is enhanced. On the heater chip for thermocompression bonding, a small projection-like thermocompression bonding portion (2) heated up by conduction resistance is provided on a small plate-like body (1), at the front of the plate of reduced width. A cut (3) is provided at the end of the body, toward the vicinity of the thermocompression bonding portion. Both sides of the cut serve as conduction terminals (1a, 1b). A thermocouple (5) for temperature detection is installed in the vicinity of the thermocompression bonding portion (2). A projection portion (7) for thermo-welding the temperature detection portion of the thermocouple is provided on the inner side surface of the cut or on the outer peripheral side surface of the body.